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ASX RELEASE **9 June 2026**

ASX: NVU

Investor Webinar Presentation

Nanoveu Limited (ASX: NVU, OTCQB: NNVUF) ("Nanoveu" or the "Company"), a technology innovator across advanced semiconductor, visualisation, and materials science, is holding its webinar commencing at 12.00 pm (AWST) / 2.00 pm (AEST) today.

The presentation materials are attached for the information of investors and can also be accessed via the "Announcements" page of the Company's website https://nanoveu.com/.

Key highlights to be discussed:

- 22nm ECS-DoT commercial roadmap and design-in activity;
- Completed 16nm ECS-DoT tape-out and technical catalysts;
- ECS-DoT Drone Program including live drone trials; and
- Acquisition of Spinoff Robotics

If you would like to join, please click on the link below to register:

Date: Tuesday, 9 June 2026

Time: 12.00 pm Australian Western Standard Time (AWST) / 2.00 pm Australian Eastern Standard Time (AEST)

Invite link: https://zoom.us/webinar/register/WN_a31Y8rkJRhqpeV27qXwRFQ

This announcement has been authorised for release by the Board of Directors.

-ENDS-

Nanoveu Media
Alfred Chong, Nanoveu MD and CEO
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About Nanoveu Limited

Further details on the Company can be found at https://nanoveu.com/.

EMASS is a pioneering technology company specialising in the design and development of advanced systems-on-chip (SoC) solutions. These SoCs enable ultra-low-power, AI-driven processing for smart devices, IoT applications, and 3D content transformation. With its industry-leading technology, EMASS will enhance Nanoveu's portfolio, empowering a wide range of industries with efficient, scalable AI capabilities, further positioning Nanoveu as a key player in the rapidly growing 3D content, AI and edge computing markets.

EyeFly3D™ is a comprehensive platform solution for delivering glasses-free 3D experiences across a range of devices and industries. At its core, EyeFly3D™ combines advanced screen technology, sophisticated software for content processing, and now, with the integration of EMASS's ultra-low-power SoC, powerful hardware.

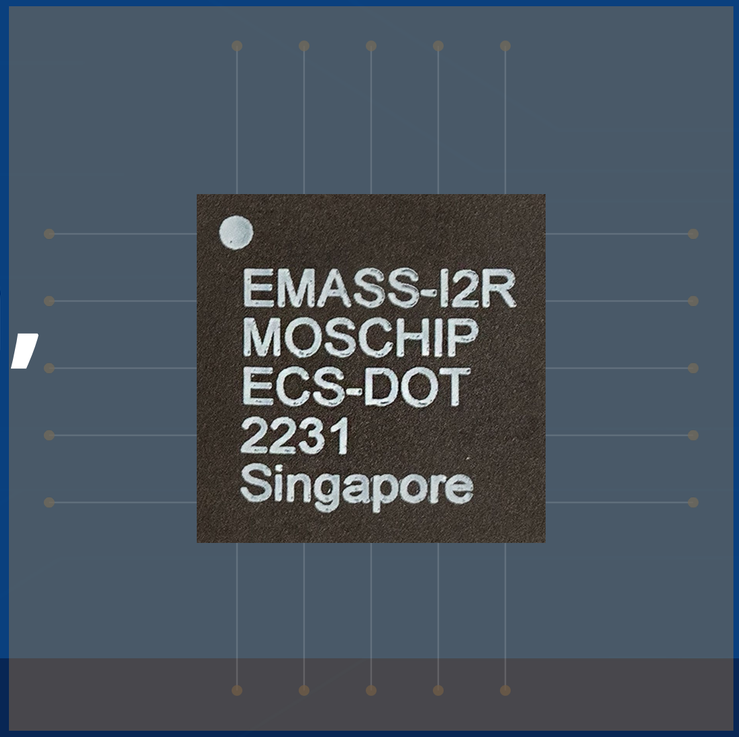
Nanoshield™ is a self-disinfecting film that uses a patented polymer of embedded Cuprous nanoparticles to provide antiviral and antimicrobial protection for a range of applications, from mobile covers to industrial surfaces. Applications include *Nanoshield™ Marine*, which prevents the growth of aquatic organisms on submerged surfaces like ship hulls, and *Nanoshield™ Solar*, designed to prevent surface debris on solar panels, thereby maintaining optimal power output.

Forward Looking Statements This announcement contains 'forward-looking information' that is based on the Company's expectations, estimates and projections as of the date on which the statements were made. This forward-looking information includes, among other things, statements with respect to the Company's business strategy, plans, development, objectives, performance, outlook, growth, cash flow, projections, targets and expectations and related expenses. Generally, this forward-looking information can be identified by the use of forward-looking terminology such as 'outlook', 'ambition', 'anticipate', 'project', 'target', 'potential', 'likely', 'believe', 'estimate', 'expect', 'intend', 'may', 'mission', 'would', 'could', 'should', 'scheduled', 'will', 'plan', 'forecast', 'evolve' and similar expressions. Persons reading this announcement are cautioned that such statements are only predictions, and that the Company's actual future results or performance may be materially different. Forward-looking information is subject to known and unknown risks, uncertainties and other factors that may cause the Company's actual results, level of activity, performance, or achievements to be materially different from those expressed or implied by such forward looking information.

nanoveu

INVESTOR WEBINAR· JUNE 2026

Ultra-low-power silicon, for the edge



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EMASS a nanoveu business | SPINOFF ROBOTICS

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AUTHORISATION This document has been authorised for release by the Company's Board of Directors.

A fabless semiconductor innovator in edge AI processing

Ultra-low-power edge-AI SoCs at the sub-milliwatt tier where wearables, hearables, drones and sensor nodes need intelligence in µW–mW budgets. No other existing general-purpose chip architecture delivers it.

SILICON

<1 mW

Always-on AI inference
The lowest average power in the named competitive set [1]

[1] *MLCommons, May 2025*

GLOBAL

3 sites

Global Presence
R&D centres in Singapore and Egypt; commercial team headquartered in the USA

COMMERCIALISATION

5 markets

Edge-AI verticals in development
Wearables, hearables, smart devices, industrial and robotics, and drones

SILICON

<10 ms

Inference Latency
Real-time response at the sensor, no cloud round-trip or host wake-up

IN-HOUSE

100 %

Acquired by Nanoveu (ASX:NVU)
Completed in March 2025

ROADMAP

22 nm + 16 nm

Acquired by Nanoveu (ASX:NVU)
ECS-DoT-22 sampling now; ECS-DoT-16 tapeout complete

Capital structure

ASX / OTCQB CODE	NVU / NNVUF
PREVIOUS CLOSE	$0.049
MARKET CAP	$52.94m
SHARES ON ISSUE	1,080.4m
OPTIONS ON ISSUE	269.9m
Q1 2026 CASH	$6.67m

LISTING

Dual-listed in Australia (ASX) and the United States (OTCQB)

All figures in AUD unless stated. As at close 8 June 2026.

Board and Management

GROUP CEO

Alfred Chong

Group CEO & Director

- Founder of Nanoveu; 30+ years scaling tech companies
- Former CEO of Atex Media Command (APAC), THISS Technologies, 121View
- Former CMO at 3D International

CHAIRMAN

Dr. David Pevcic

Executive Chairman

- Experienced investor across resources and technology
- Non-Executive Chairman, Battery Age Minerals (ASX: BM8)
- Non-Executive Chairman, Infini Resources (ASX: I88)
- BSc, MBBS — University of Western Australia

CTO

Dr. Mohamed Sabry

EMASS Founder & Director

- CTO & Founder of EMASS
- Associate Professor, NTU Singapore; postdoc Stanford
- Recipient, Nanyang Education Award
- Ph.D. from EPFL

CFO

Raymond Chen

CFO & Director

- 15+ years across resources and corporate finance
- Roles at Iluka, NRW Holdings, Equinox Resources, KPMG
- MBA, Cambridge Judge Business School

NED

Steve Apedaile

Non-Executive Director

- 30 years' experience in accounting
- Worked at KPMG and Horwath Hong Kong
- Fellow of ICAEW, Member of AICD
- Executive Chairman of Sprintex (ASX: SIX)

Built by veterans of the silicon industry

CTO & FOUNDER

Dr. Mohamed Sabry

Founder of EMASS

- Associate Professor, NTU Singapore
- Postdoc, Stanford University
- Ph.D. from EPFL
- Recipient, Nanyang Education Award

CEO SEMICONDUCTOR

Mark Goranson

CEO of Semiconductor Technology

- VP of Global Ops, TE Connectivity
- SVP of Fab Ops, ON Semiconductor
- VP of Fab Ops, Freescale
- Early team member of Intel

SALES & MARKETING

Scott Smyser

VP, Sales & Marketing

- EVP Marketing & BD, Si-Ware Systems
- VP & GM, VTI Technologies (Murata)
- SVP Sales, Atomica
- SVP Strategic Sales, Rockley Photonics

TINYML — THE MICRO-EDGE AI MARKET

A market growing from $30.7B to $68.7B in five years

AI inference is moving off the cloud and onto the device. Always-on TinyML silicon is the foundational layer enabling that shift.

TINYML MARKET SIZE

$30.7B → **$68.7B**

2026 2031

Tiny Machine Learning, always-on ML running locally on resource-constrained microcontrollers and SoCs. The segment where EMASS targets.

17.5%
CAGR, 2026–2031

$3.3B
Ultra-low-power AI chip SAM by 2027

5.9B
TinyML chipset shipments by 2030

Sources: Roots Analysis, Tiny Machine Learning Market 2026–2040; Iterathon, TinyML Industrial IoT Production Deployment 2026; ABI Research, TinyML Inference Chipset Shipments 2024. Third-party forecasts; not company guidance.

WHAT'S DRIVING DEMAND

- Users expect voice, motion and health monitoring to run continuously without daily charging
- Privacy, latency and connectivity costs are pulling AI off the cloud and onto the device
- On-device intelligence is increasingly becoming the baseline expectation across consumer and industrial
- No existing general-purpose chip architecture delivers always-on AI within the sub-mW budget that battery devices demand

EMASS is purpose-built for this market: ultra-low-power AI inference silicon designed from the ground up for always-on operation at the sensor edge.

AI moving to the edge. Power is the barrier

Current chip architectures each break down somewhere on the path to always-on, on-device intelligence.

CLOUD AI

Powerful, but remote

- Latency makes real-time response unreliable
- Bandwidth and inference cost scale with device fleet
- Privacy and connectivity constraints limit deployment

APP PROCESSORS / MCUS

Not built for AI

- 100 mW–1 W+ to keep AI workloads alive continuously
- No efficient way to monitor sensors continuously
- Form factor and battery pay the price

NPUS / GPUS

Too power-hungry

- Optimised for burst inference, not always-on
- 10s–100s of mW even at light workloads
- Single-modality acceleration in most designs

THE MICRO EDGE

EMASS plays at the micro edge — the sub-milliwatt, always-on tier of the edge-AI market where wearables, hearables, drones and sensor nodes need intelligence in µW–mW budgets. No existing general-purpose chip architecture delivers it.

EMASS does not compete in the macro or meso edge. ECS-DoT operates in the sub-milliwatt tier where general-purpose silicon — cloud accelerators, application processors, NPUs — structurally cannot.

An AI co-processor that sits at the sensor edge

Purpose-built for the micro edge, the always-on power budget that wearables, hearables and drones demand. Integrates into existing system architectures without redesign.

- **Sits between sensors and the main MCU/processor:** interfaces directly with sensors, processes data continuously at sub-mW power
- **Offloads always-on AI from the system:** no need to keep the main MCU/processor active, reducing system power significantly
- **Event-driven system activation:** wakes the main MCU only when meaningful events occur
- **Drop-in integration:** works with existing MCUs/processors and sensor stacks; no need to redesign core system architecture

VS. EXISTING ARCHITECTURES

	APP PROC.	MCU	MCU + NPU	ECS-DoT
Power	500 mW–2 W	50–200 mW	10–50 mW	**<1–5 mW**
Always-on AI	No	No	Limited	**Yes**
Multi-modal	Partial	No	No	**Yes**
AI co-processor	No	No	No	**Yes**
Battery impact	High	Moderate	Moderate	**Minimal**

Always-on intelligence in a sub-milliwatt envelope.

A programmable system-on-chip purpose-built for edge AI. Co-designed from device physics through algorithms. Same silicon drops into wearables, hearables, AI cameras, IoT and drones.

<1–5 mW

Always-on AI inference

Sensors, vision, audio and motion processed continuously without draining the battery.

Multi-modal

Sensor fusion on one chip

Audio, vision and motion combined in real time — the heart of meaningful edge intelligence.

No external memory

Simpler, smaller systems

All AI compute runs on-chip. Smaller BOM, smaller board, smaller product.

<10 ms

Inference latency

Real-time response without round-tripping to the cloud or waking the host.

VS. EXISTING ARCHITECTURES

	APP PROC.	MCU	MCU + NPU	ECS-DOT
Power	500 mW–2 W	50–200 mW	10–50 mW	**<1–5 mW**
Always-on AI	No	No	Limited	**Yes**
Multi-modal	Partial	No	No	**Yes**
AI co-processor	No	No	No	**Yes**
Battery impact	High	Moderate	Moderate	**Minimal**

EXCEPTIONAL AT TASK EFFICIENCY

20X more than the competition

Independently benchmarked against the leading commercially-available edge-AI chips. ECS-DoT lets battery-constrained devices run always-on AI for orders of magnitude longer.

Benchmark	Metric	ECS-DoT-22	NDP120 (Syntiant)	Apollo 4 (Ambiq)
Visual Wake Words	Latency (ms)	**4.2**	12.72	N.A.
	Energy (µJ)	**3.7**	71.71	N.A.
Image Classification	Latency (ms)	**6.2**	15.98	70–160*
	Energy (µJ)	**5.5**	101.83	~2100**
Keyword Spotting	Latency (ms)	**3.9**	4.37	22–54*
	Energy (µJ)	**3.07**	31.54	~360**
Anomaly Detection	Latency (ms)	**1.2**	N.A.	2.28–5.73*
	Energy (µJ)	**0.8**	N.A.	~150**

*Source: MLCommons, 2025. *Execution time extrapolated from Ambiq comparison claims. **Numbers extracted from MLPerf Tiny benchmark report.*

WHY IT MATTERS

Energy per inference

10–20× lower than Syntiant
100–400× lower than Ambiq
Directly extends battery life or shrinks battery size

Latency

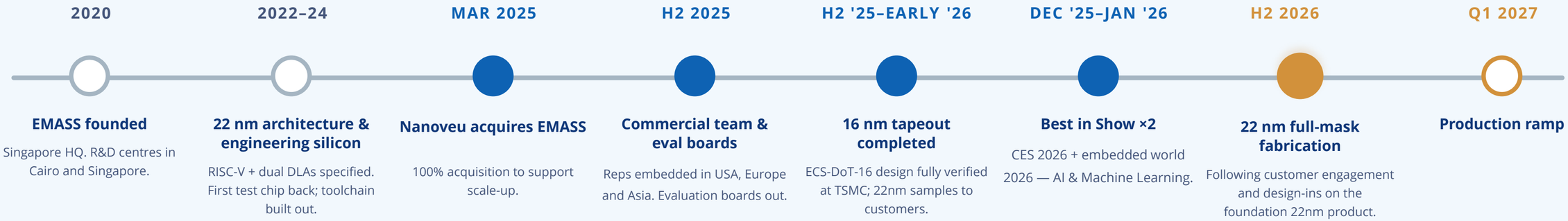
2–3× faster than Syntiant
5–25× faster than Ambiq
Real-time response at the sensor, no host wake-up

Energy and latency are the two metrics that determine whether always-on AI is viable on a battery-powered device. ECS-DoT leads on both.

22 NM → 16 NM · THE ROAD TO COMMERCIAL SILICON

Years of engineering behind two advanced-node products

ECS-DoT-22 in customer engagement today, targeting production ramp Q1 2027. ECS-DoT-16 tapeout complete; awaiting first samples from TSMC.



22 NM · IN CUSTOMER ENGAGEMENT

ECS-DoT-22 — full-mask fabrication ahead

- Dual DLAs + RISC-V validated in engineering silicon
- 4 MB on-chip MRAM/SRAM, no external DRAM
- Eval boards and SDK in customers' hands

NEAR-TERM CATALYST

16 NM · TAPEOUT COMPLETE

ECS-DoT-16 — awaiting first samples

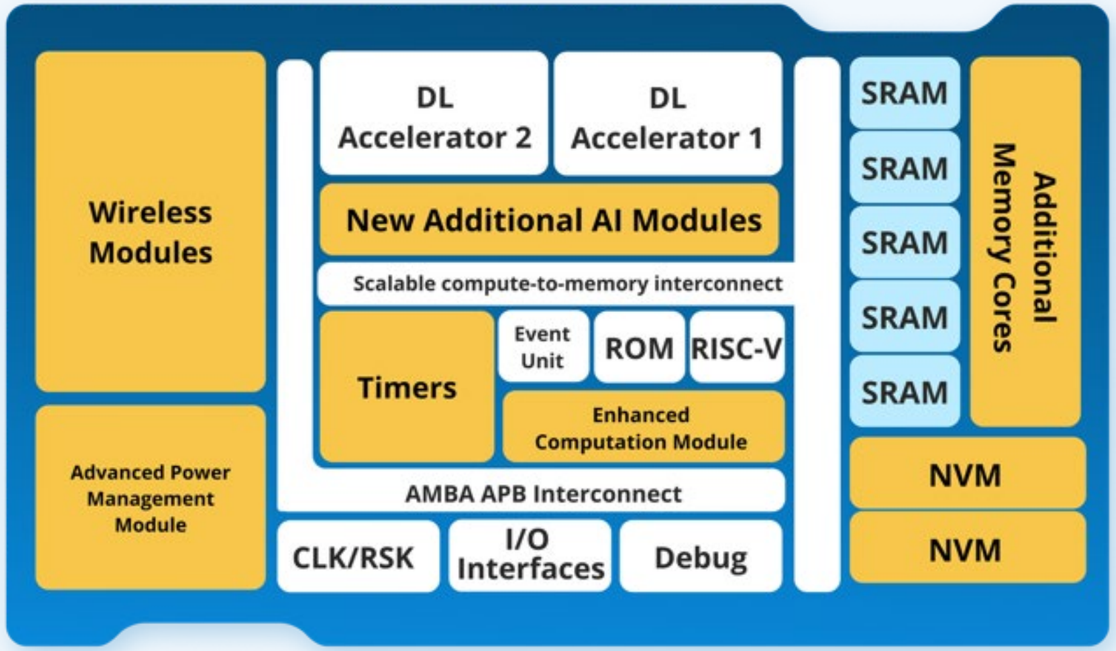
- Integrated BLE eliminates external wireless ICs
- Dedicated AI module: YOLO-Nano, MobileNet-SSD, FOMO
- Adaptive power mgmt + integrated FPU + expanded memory

Refs: 17 Dec '25, 27 Jan '26 announcements. Company aspirations that should not be read as forward-looking statements.

What's New in our 16nm ECS-DoT

Five targeted upgrades over the 22nm baseline

16nm Architecture



Refs: 17 Dec '25, 27 Jan '26 announcements

Key Improvements

Smarter AI Compute

- Dedicated object detection AI module
- Integrated FPU
- *Enhanced computation module handles larger, more complex models on-chip*

Lower Power, Longer Battery

- Adaptive power management
- Expanded on-chip memory and NVM
- *Less energy per inference, fewer external accesses*

Wireless Built-in

- Fully integrated low energy Bluetooth (BLE)
- *Single-chip connectivity, with wireless integration built-in*

Every upgrade targets a real customer constraint: model size, battery life, or board cost

Independently validated award-winning silicon

ECS-DoT won Best in Show for AI & Machine Learning at two of the industry's largest events.

- Major accolades for innovative architecture and superior performance
- Ultra-low-power, RISC-V based SoC delivering real-time edge-AI processing for vision, audio and sensor data
- Showcased multiple live demos including predictive maintenance, audio security detection, wrist-worn wearable and bone-conduction audio
- Validated by independent benchmarking against the leading commercially-available edge-AI chips

2026
CES (Las Vegas)

2026
embedded world (Nuremberg)

TARGET VERTICALS

Five markets where ECS-DoT excels

Each independently sized in the hundreds of billions to over a trillion. ECS-DoT addresses the always-on, sub-milliwatt slice of each.

Wearables

Smartwatches, smart bands, smart rings, AR/VR glasses

Always-on sensor fusion for health, motion, and immersive experiences in multi-day battery budgets.

$368.4B

by 2035 · Fact.MR

Hearables

Earbuds, headphones, hearing aids

Local keyword spotting, motion-triggered wake-up, bone-conduction audio.

$138.5B

by 2029 · MarketsandMarkets

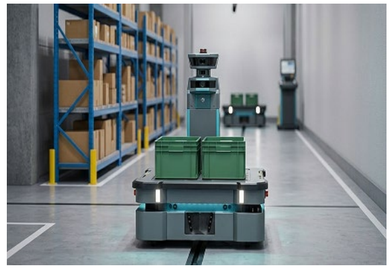
Smart Devices

AI cameras, smart remotes, game controllers, smart locks

On-device intelligence for voice, vision, and presence detection in always-listening consumer products.

$537.3B

by 2030 · Grand View Research



Industrial and Robotics

Predictive maintenance, asset tracking, autonomous robots

Always-on inference for predictive maintenance, asset tracking, and autonomous control in factory and field environments.

$497.8B

by 2030 · Statista

Drones

Commercial, defence, inspection

Onboard inference, longer flight times, systems-level engagement via NTU IP and Spinoff Robotics.

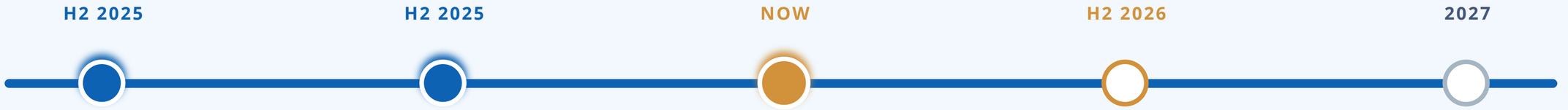
$223.7B

by 2034 · Fact.MR

CUSTOMER ENGAGEMENT PIPELINE

Active engagement across multiple OEMs

From first eval boards out to active application development today.
First customer design-ins targeted for H2 2026.



Eval boards out

Market evaluations begin. ECS-DoT-22 sampling to lead OEMs.

OEM evaluation

Multiple OEMs start evaluating across wearables, hearables and IoT.

Application development

OEMs building product applications around ECS-DoT. SDK in customer hands.

Design-ins

First commercial design-ins targeted. 22 nm full mask tapeout in CY Q3 2026.

Production ramp

Targeted production ramp of 22nm. 16 nm next-gen ECS-DoT in customer hands.

SALES MOTION

Distributors embedded in OEM hubs

Strategic coverage across wearables, hearables, consumer and industrial IoT, drones and defence — ECS-DoT positioned as exclusive Edge-AI SoC.

DEVELOPER ENABLEMENT

Eval board + SDK shipping

Eval board in customer hands. EDI toolchain imports PyTorch / TF Lite / Caffe.

PARTNER CHANNELS

Arrow & Semtech extending reach

Arrow Electronics distribution + reference designs. Semtech LoRaWAN+ECS-DoT demos co-marketed.

Refs: NVU Investor Webinar (10 Sep '25), HK Ignite (16 Oct '25). Company aspirations that should not be read as forward-looking statements.

THE SALES CYCLE

Every customer win is a design-in.

From first contact to locked-in silicon, every engagement is a hands-on, technical sell that ends with ECS-DoT engineered into the customer's product.

6–12 mo

TYPICAL DESIGN-IN

START · HANDS-ON EVAL · ENGINEERING · OUTCOME

01

Lead generation

Identify and qualify design teams building battery-powered, AI-at-the-edge products that need our power envelope.

TOP OF FUNNEL

02

Evaluation board

Ship the ECS-DoT eval board so the customer can benchmark it hands-on against their own workload and hardware.

PROOF ON THEIR BENCH

03

AI model porting

Port and quantize the customer's own AI model onto ECS-DoT — the deep technical work that aims to turn interest into commitment.

✓ Completed for 2 potential customers

04

Design win

ECS-DoT is locked into the customer's design and carried into volume production — recurring, per-unit revenue.

→ VOLUME PRODUCTION

22 nm ECS-DoT is on Silicon and undergoing customer sampling.

Commercialisation pathway is underway today. Multiple evaluation boards in customers' hands and active design-ins progressing across six edge-AI markets.

DESIGN-IN ACTIVE

Asset tracking

Always-on location and condition sensing for cold-chain and logistics assets, at sub-milliwatt power budgets.

DESIGN-IN ACTIVE

Smart ring

On-device health, motion and gesture inference inside the tightest wearable power and form-factor envelope.

DESIGN-IN ACTIVE

Gas sensing

Continuous leak and air-quality detection with local anomaly classification — no cloud round-trip required.

DESIGN-IN ACTIVE

Predictive maintenance

On-device vibration and acoustic anomaly detection for always-on industrial equipment monitoring.

DESIGN-IN ACTIVE

Dash cams

Real-time on-device object and event detection, keeping inference local within the camera's power limits.

DESIGN-IN ACTIVE

Hearables

Local keyword spotting and motion-triggered wake-up with sub-10 ms on-device response.

Strategic partners extending our reach

ARROW

NYSE: ARW

Global technology distributor & engineering partner
2024 sales US$28B

- Enhanced SDKs, developer tools and reference designs
- Predictive maintenance reference design shipped
- Cold asset tracking design in development
- Co-marketing to expand customer reach

DISTRIBUTION | REFERENCE DESIGNS | ENGINEERING ENABLEMENT

SEMTECH

NASDAQ: SMTC

Global semiconductor provider
2024 sales US$800M+

- LoRaWAN transceiver combined with ECS-DoT
- Demo showcased at CES 2026
- Predictive maintenance and security detection reference designs
- Co-marketing to expand customer reach

LORAWAN | REFERENCE DESIGNS | CO-MARKETING

MANUFACTURING & TECHNICAL PARTNERS

Built with the world's most trusted semiconductor partners

Advanced-node manufacturing, leading-edge process research, design services and a deep talent pipeline, the foundations behind every ECS-DoT chip.

FOUNDRY HSINCHU, TAIWAN

Taiwan Semiconductor Manufacturing Co.

The world's largest pure-play foundry — fabricating ECS-DoT-16 (16 nm FinFET) and ECS-DoT-22 (22 nm) silicon at production scale.

PROCESS R&D LEUVEN, BELGIUM

imec

World-leading nanoelectronics research centre. Collaboration on next-generation process technology, MRAM integration and low-power AI silicon.

DESIGN SERVICES HYDERABAD, INDIA

MosChip Technologies

Turnkey ASIC and semiconductor engineering services — physical design, DFT, package and signoff support across the ECS-DoT roadmap.

RESEARCH & TALENT CAIRO, EGYPT

The American University in Cairo

Talent pipeline feeding our Cairo R&D centre — RTL, verification and embedded-AI engineering.

WHY IT MATTERS A de-risked supply chain across four continents — production-grade foundry, leading-edge process IP, world-class design services, and a continuous engineering talent pipeline.

SECTION II

Drones, from silicon to systems-level solutions.

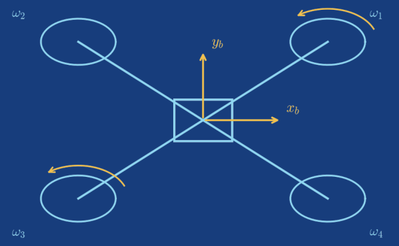
WHY

Two Major Challenges. One Chip Solution.

Energy-optimal flight control = **real-time physics × onboard AI** , fused on the **EMASS ECS-DoT**

FLIGHT DYNAMICS & CONTROL

rigid-body dynamics · constrained **MPC** · power-optimal allocation



$$m\dot{\mathbf{v}} = R\,f_T\,\mathbf{e}_3 - mg\,\mathbf{e}_3 - D(\mathbf{v} - \mathbf{v}_{wind})$$

$$J\dot{\boldsymbol{\omega}} = \boldsymbol{\tau} - \boldsymbol{\omega} \times J\boldsymbol{\omega}, \quad \dot{R} = R\hat{\boldsymbol{\omega}}$$

$$\min_{u_{0..N-1}} \sum_{k=0}^{N-1} \|x_k - x_k^{ref}\|_Q^2 + \|u_k\|_R^2$$

$$\text{s.t.} \quad x_{k+1} = f(x_k, u_k), \quad u_{min} \le u_k \le u_{max}$$

$$P_i \propto \frac{T_i^{3/2}}{\sqrt{2\rho A}}, \qquad E = \int_0^{t_f} P\,dt \to \min$$

$$[f_T,\ \tau_x,\ \tau_y,\ \tau_z]^T = M\,[\omega_1^2,\ \omega_2^2,\ \omega_3^2,\ \omega_4^2]^T$$

SENSOR & MISSION INPUTS

- Position & Velocity
- Airframe Model (param.)
- Barometric Pressure
- Rotor RPM feedback
- Roll · pitch · yaw (IMU)
- GPS target waypoints
- Battery State of Charge
- Wind estimate (inferred)

REAL-TIME PHYSICS

EMASS

ECS-DoT

fusion · MPC · NN inference

ONBOARD AI

OUTPUT · TARGET VELOCITY COMMANDS

Trajectory shaped in real time

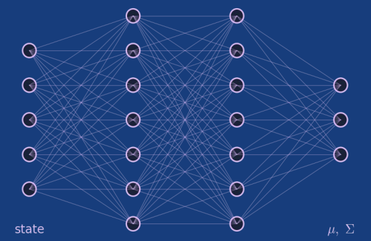
to maximize flight endurance

mW-class
power envelope

35 Hz loop
kHz-rate I/O

EDGE AI · LEARNED CONTROL

constrained **PPO** policy · NN inference · INT-quantized deployment



$$h^{(l+1)} = \sigma(W^{(l)} h^{(l)} + b^{(l)})$$

$$L^{CLIP}(\theta) = \hat{E}_t\left[\min\left(r_t(\theta)\hat{A}_t,\ \text{clip}(r_t, 1-\epsilon, 1+\epsilon)\hat{A}_t\right)\right]$$

$$\max_{\pi} \min_{\lambda \ge 0} J_R(\pi) - \lambda(J_C(\pi) - d)$$

$$\hat{w} = s \cdot \text{clamp}(\lfloor w/s \rceil,\ -2^{b-1},\ 2^{b-1}-1)$$

$$\delta^{(l)} = (W^{(l+1)})^T \delta^{(l+1)} \odot \sigma'(z^{(l)})$$

$$\pi_\theta(a \mid s) = \mathcal{N}(\mu_\theta(s),\ \Sigma_\theta(s))$$

PROOF IN THE AIR

Off the bench. Into the air.

Not a simulation, not a render — this is the **ECS-DoT flying a real airframe** , closing the full control loop on-chip, **one test flight at a time**.

SEVERAL FRONTS AT ONCE

Endurance, control, onboard navigation and platform integration are all advancing in parallel.

MAJOR PROGRESS HAS BEEN ACHIEVED

Full flight control at **mW-class power, entirely on-chip** , has never been done on an edge device this small. There is no reference design to copy.

REFINED IN REAL CONDITIONS

Real flight means wind, payload shifts and sensor noise. The control loop is being tuned and re-tuned across these conditions, getting tighter with every flight.

BUILT TO SCALE

Core flight control runs on a single chip today. The same approach is designed to scale across larger platforms and extend into wider capability over time.

WHY DRONES ARE DIFFERENT

In drones, we are developing systems, not just silicon to capture more value.

The Spinoff Robotics acquisition gives Nanoveu a deployment surface for ECS-DoT silicon, and the engineering capability to develop every layer above it.

STEP 1 · IP

Building capability through IP licensing

A licensing-led strategy to access proven drone-technology IP across autonomy, sensing and control, building the foundation for purpose-built platforms rather than developing every layer from scratch.

STEP 2 · PLATFORMS

Spinoff Robotics acquisition

Adds two commercially-validated proprietary drones — ALICE and METRON, plus in-house airframe, aerodynamics and flight-control engineering.

STEP 3 · SILICON

ECS-DoT engineered in

Silicon designed into the airframe from the outset — sensor placement, power envelope and control-loop latency built around ECS-DoT, not bolted on as a payload.

THE SYSTEMS-LEVEL STACK WE NOW OWN

SILICON
ECS-DoT
22 nm / 16 nm SoC, sub-mW always-on inference

AIRFRAME
Spinoff design IP
Mechanical, aero, flight-control engineering

PERSISTENCE
ALICE
Tethered platform, high payload, jam-resistant

SENSING
METRON
Sub-mm photogrammetry + AI deviation

TWO PROPRIETARY DRONE PLATFORMS, READY FOR ECS-DOT

ALICE and METRON.

ALICE HIGH-PAYLOAD DRONE PLATFORM

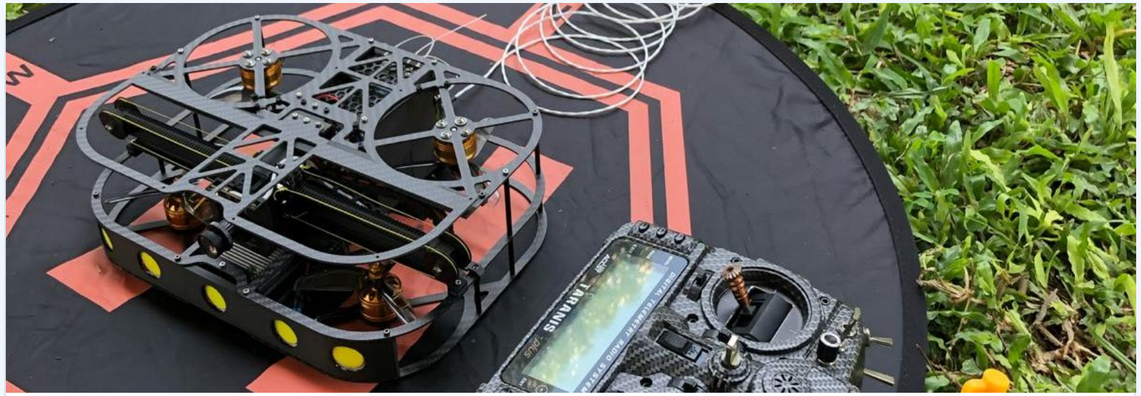
High-payload tethered drone system.

High payload: ground-side power option offloads weight from the airframe for higher-grade sensors

EW-resilient: eliminates GPS-spoof / RF-jam vectors

Rapid deploy: single-operator, sub-hour to persistent overwatch

GARDENS BY THE BAY | HTX SINGAPORE



METRON SUB-MM SENSING

Inspection in areas humans can’t get to.

Sub-millimetre accuracy: via photogrammetry in confined spaces

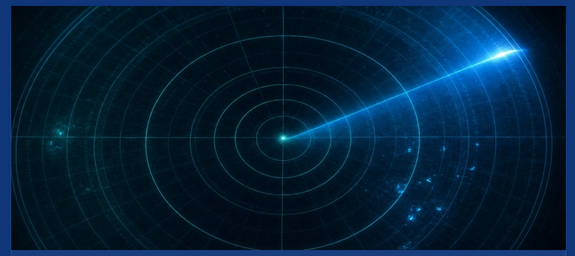
Pre-trained analytics: baseline-deviation detection on real data

Runs on ECS-DoT: at the edge, no off-platform compute or cloud

LAND TRANSPORT AUTHORITY | BRIDGE INSPECTION-PROVEN

Both platforms validated with **Tier-1 Singapore customers** — Gardens by the Bay, Land Transport Authority and Home Team Science & Technology Agency.

Four priority markets, anchored in defence.



01 · DEFENCE

$98.2B

Military UAV market by 2033 · GVR

Forward-base ISR overwatch, EW-resilient surveillance, sovereign drone capability.

02 · HYPERSCALER

$595B

Data-centre market by 2030 · MI

Perimeter security and structural monitoring across cooling, substations, switchgear.

03 · AIRPORT FOD

$1.5B

FOD detection by 2034 · DI

Tether eliminates the airspace-conflict that prevents free-flying drones operating airside.

04 · HAZARDOUS

$9.5B

Annual nuclear decom. by 2030 · MI

Reactor cores, spent-fuel pools, decommissioning programs humans cannot inspect.

Market sources: GVR, MI Research, DI Research

Defence procurement is accelerating globally, allied governments are mandating sovereign drone capability, and GPS-dependent platforms have been exposed in contested theatres.

UPCOMING CATALYSTS

The next twelve months.

Q3-Q4 2026

22 nm full mask tapeout commences

Targeted following active customer engagement on the foundation product.

Q3 2026

16 nm first samples

Tapeout recently completed; samples returning shortly for characterisation.

Q2 2026

Live drone trials

Validating Phase-2 flight endurance simulation results on ECS-DoT silicon with US specialist partner.

BY 31 AUG 2026

Spinoff acquisition close

Amalgamation of ALICE, METRON and airframe engineering team into the Nanoveu group.

CY 2026

First ECS-DoT design-ins

OEM eval boards in hand, design-in process started, more potential customer demand inbound.

ONGOING

New reference designs

Cold asset tracking, security detection, wrist-worn wearable, predictive maintenance.

ONGOING

Drone-vertical IP

Multi-chip configuration potential spanning endurance, navigation, swarm intelligence and counter-drone detection.

ONGOING

Defence engagement

Direct engagement with drone OEMs, system integrators and end users across military and commercial domains.

*Company aspirations that should not be read as forward-looking statements.

THANK YOU

Ultra-low-power silicon, at scale.

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LISTINGS

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OTCQB: NNVUF

nanoveu.com

CEMASS a nanoveu business | SPINOFF ROBOTICS